

LINQSOL™ EMC-G845

Black epoxy molding compound



- Green epoxy molding compound
- Designed for Quad Flat No Leads(QFN) and Quad Flat (QFP) packages
- Designed to satisfy JEDEC MSL 3 reliability

LINQSOL™ EMC-G845 is a halogen-free epoxy molding compound specifically developed for the encapsulation of Quad Flat No Leads(QFN), Quad Flat (QFP) packages and other thin, high-density packages. Its broad gel time and high spiral flow make it ideal for QFN and QFP molding, meeting higher flowability and wide processing window requirements. Additionally, **EMC-G845** delivers excellent performance and outstanding reliability with its UL 94 V-0 flammability rating and low water absorption. This product is deliberately formulated without the inclusion of substances prohibited by the European Union RoHS and REACH.

Overall, **LINQSOL™ EMC-G845** seamlessly integrates advanced material properties, safety compliance, and superior performance to deliver a reliable solution for semiconductor device encapsulation.

Specifications

Property	Value	Unit
General Properties		
Color	Black	–
Filler content	87	%
Filler shape	Spherical	–
Filler sieving size	75	µm
Specific gravity	1.98 ±0.02	–
Spiral flow at 175 °C	165 ±5%	cm
Melt viscosity at 175 °C	13000 ±10%	cP
Chemical Properties		
Ion content		
Chloride (Cl ⁻) concentration	<10	ppm
Sodium (Na ⁺) concentration	<15	ppm
Moisture absorption after PCT, 24h	≤0.25	%
pH of extract	5–7	–
Mechanical Properties		
Flexural strength at 25°C	150 ±5%	MPa
Flexural modulus at 25 °C	23 ±5%	GPa
Mold shrinkage	0.2 ±0.05	%
Poisson's ratio at 25 °C	0.3	–

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Property	Value	Unit
Electrical Properties		
Dielectric constant at 1 MHz	3.8	–
Dissipation factor at 1 MHz	0.004	–
Thermal Properties		
Glass transition temperature	128 $\pm$ 5	°C
Coefficient of thermal expansion, α_1	11	ppm/°C
Coefficient of thermal expansion, α_2	36	ppm/°C
Gel time at 175°C	55 $\pm$ 5	s
Thermal conductivity	0.88 $\pm$ 0.02	W/mK
Flammability rating	V-0	UL-94

Recommended mold parameters

Parameters	Value	Unit
Molding temperature	170–180	°C
Transfer pressure	70–150	kg _f /cm ²
Transfer time	8–25	sec
Cure time at 175°C	100–180	sec
Post mold cure time at 175°C	4–8	h

The curing conditions provided are recommended guidelines based on typical laboratory results. Actual curing parameters should be defined and validated by the user to ensure compatibility with specific materials, part geometries, and end-use requirements. It is the user's responsibility to optimize and confirm curing conditions that meet their performance and quality standards.

Processing Instructions

- Before use, let **LINQSOL™ EMC-G845** reach room temperature (23 °C $\pm$ 5) for 16 hours. Keep the bag unopened and stored in a dry location with a relative humidity of $\leq$ 50% during thawing to prevent moisture contamination.
- Use the materials within 24 hours after removing the container from cold storage.

Storage and Handling

LINQSOL™ EMC-G845 is available in pressed pellets in a wide range of sizes to meet specific customer needs. To ensure product integrity, keep it away from oxidizing materials. For long-term storage, maintain a cold environment. The shelf life when stored below 5 °C is 183 days.

The technical information presented in this document is provided for reference only and does not constitute a guarantee of specific properties or performance. Actual results may vary depending on individual conditions and application methods. Users are strongly advised to perform their own testing and validation to determine suitability for their intended use and compliance with relevant regulations.

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